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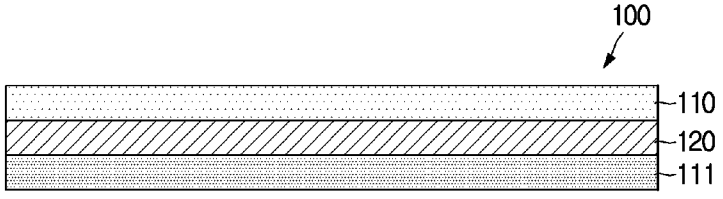
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(54) Title: ADHESIVE FILM FOR SEMICONDUCTOR



(57) Abstract: An adhesive film for semiconductor is disclosed. The present invention provides an adhesive film for semiconductor used in semiconductor packaging, comprising an adhesive layer, wherein the adhesive layer has surface tension of 19 to 52 erg/cm at 60 °C. Accordingly, the adhesive film for semiconductor according to the present invention may prevent bubbles from being formed between the adhesive film and a supporting member by controlling surface tension in an optimum condition, and also obtain higher reliability in use of the adhesive film in the semi-conductor packaging by controlling tackiness and adhesive force in an optimum condition.

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